

Broadband Blocks - Opti-Cap®

Description

- Resonance Free DC Blocking to >40GHz
- Surface Mountable by Solder or Epoxy Bonding
- Available in Tape & Reel or Waffle Pack Format
- Low Frequency Stability over Temperature
- Very Low Series Inductance
- 0201, 0402 or 0603 footprints

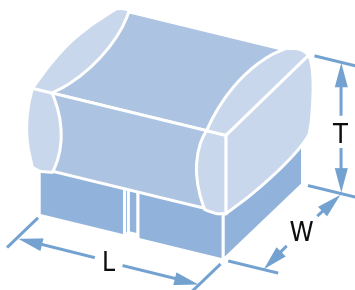
Functional Applications

- Improved Low Frequency Stability over Temperature
- Very Low Series Inductance
- X7R Temperature and Voltage Stability



Case Sizes

Case Size	Length (L)	Milli-Cap® Width (W)	Thickness (T)	Length (L)	MLC Width (W)	Thickness (T)
P21 (0201)	0.022" ± 0.006"	0.012" ± 0.002"	0.012" ± 0.002"	0.022" ± 0.002"	0.011" ± 0.001"	0.011" ± 0.003"
P42 (0402)	0.038" ± 0.004"	0.020" ± 0.002"	0.020" ± 0.002"	0.040" ± 0.002"	0.020" ± 0.002"	0.020" ± 0.002"
P62 (0603)	0.058" ± 0.003"	0.020" ± 0.002"	0.020" ± 0.002"	0.067" ± 0.004"	0.031" ± 0.004"	0.031" ± 0.005"



Part Numbers

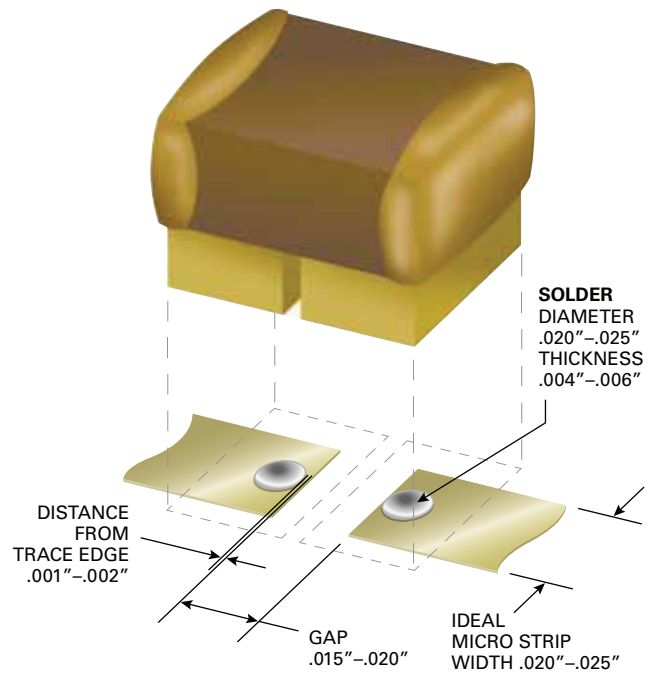
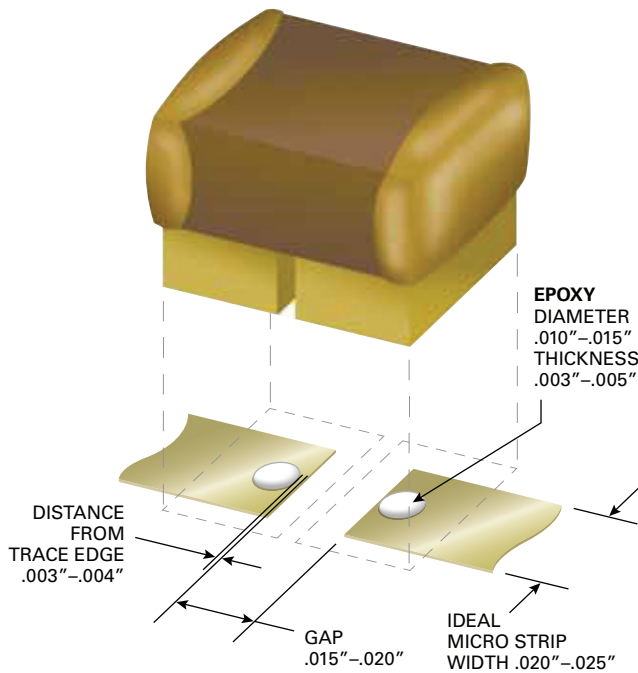
Part Number	Capacitance		Voltage Rating	TCC	IR @ +20°C	DF @ 1KHz	Aging Rate %/Decade Hr	Freq. Range 3dB (TYP)
	MLC	Milli-Cap®						
P21BN300MA03976	10nF	30pF	10V	X5R	>10 ² MΩ	3.5%	1.0%	16KHz- >40GHz
P21BN300MA04282	22nF	30pF	10V	X5R	>10 ² MΩ	3.5%	1.0%	
P21BN300MA04572	22nF	30pF	10V	X5R	>10 ² MΩ	3.5%	1.0%	
P21BN300MA04678	1.5nF	30pF	10V	X5R	>10 ² MΩ	3.5%	1.0%	
P21BN300MA04733	100nF	30pF	10V	X5R	>10 ² MΩ	3.5%	1.0%	
P42BN820MA03152	220nF	82pF	10V	X5R	>10 ² MΩ	3.5%	1.0%	
P42BN820MA04679	22nF	82pF	50V	X7R	>10 ² MΩ	3.5%	1.0%	
P62BN820MA02636	100nf	82pF	10V	X7R	>10 ² MΩ	3.5%	1.0%	

Notes:

- X5R: -55°C to +85°C ΔC ±15%
- X7R: -55°C to +125°C ΔC ±15%
- Termination Metallization 7.5μ" Au over 50μ" Ni
- Recommended attachment is solder or conductive epoxy
- Maximum assembly process temperature 250°C
- For best high frequency performance attach Milli-Cap® side to transmission line
- Recommended microstrip gap length is 0.015"

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Attachment Methods



Recommended Attachment to Soft or Hard Substrate Using Conductive Epoxy:

1. Place a single drop of conductive epoxy onto each micro strip as illustrated; the edge of the epoxy shall be at least .003\"-.004\" back from the edge of the trace to prevent filling the gap with epoxy.
2. Centering the termination gap of the capacitor within the gap in the micro strip, press with careful, even pressure onto the micro strip ensuring the terminations make good contact with the epoxy drops.
3. Cure according to the epoxy manufacturer's preferred schedule, typically 125°C to 150°C max.
4. After curing, inspect joint for epoxy shorts across the termination and micro strip gaps that would cause a short across the cap.

Isopropanol, and Methanol are both safe to use to pre clean Opti-Caps®.

Isopropanol, and Methanol are not to be used after mounting with conductive epoxy as they act as a solvent!

Recommended Attachment to Soft or Hard Substrate Using Solder:

1. Place a single drop of solder paste onto each micro strip as illustrated; the edge of the solder shall be at least .001\"-.002\" back from the edge of the trace to prevent filling the gap with solder.
2. Centering the termination gap of the capacitor within the gap in the micro strip, press with careful, even pressure onto the micro strip ensuring the terminations make good contact with the drops of solder paste.
3. Reflow according to the solder manufacturer's preferred profile, ensuring the reflow temperature does not exceed 250°C.
4. After the reflow step is completed, inspect joint for voids or excess flux and non-reflowed solder balls that can degrade performance or cause shorts across the gaps. Proper cleaning after the reflow process is crucial to avoiding performance degradation and discovering poor solder joints.

Isopropanol, and Methanol are both safe to use with soldered Opti-Caps®.

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